



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

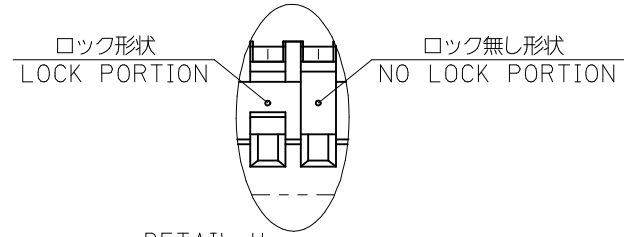
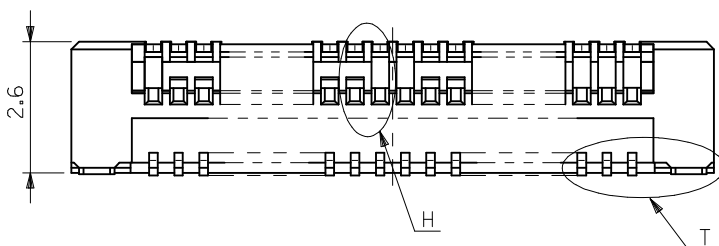
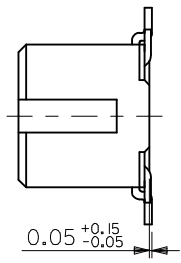
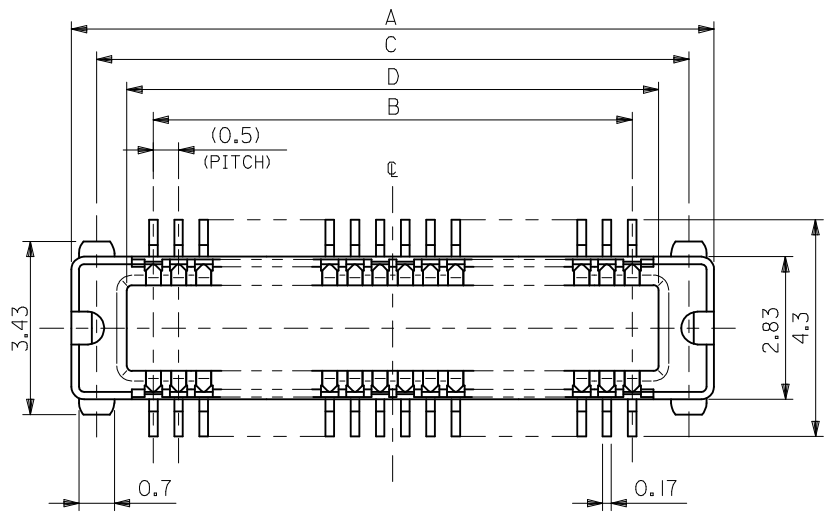
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



注記
NOTES:

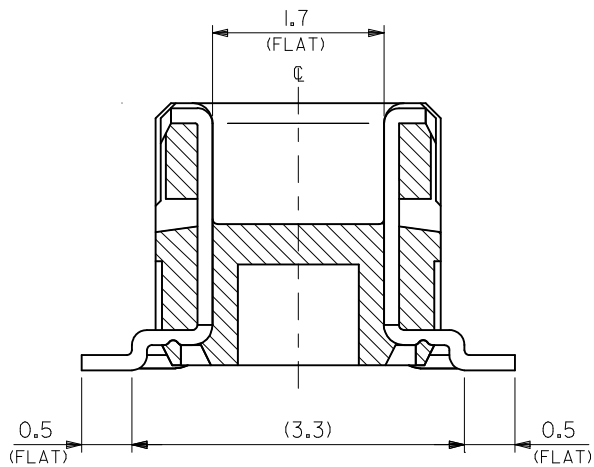
1. 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
2. メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上。
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM.
半田付け部: 金メッキ 0.4マイクロメートル以下。
SOLDER TAIL AREA: GOLD 0.4 MICROMETER MAXIMUM.
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上。
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM.
ネイル
NAIL
錫メッキ 1.0マイクロメートル以上。
TIN 1.0 MICROMETER MINIMUM.
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上。
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 54363-***
MATED CONN.: 54363-***
5. 本製品は55299-***1の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55299-***1



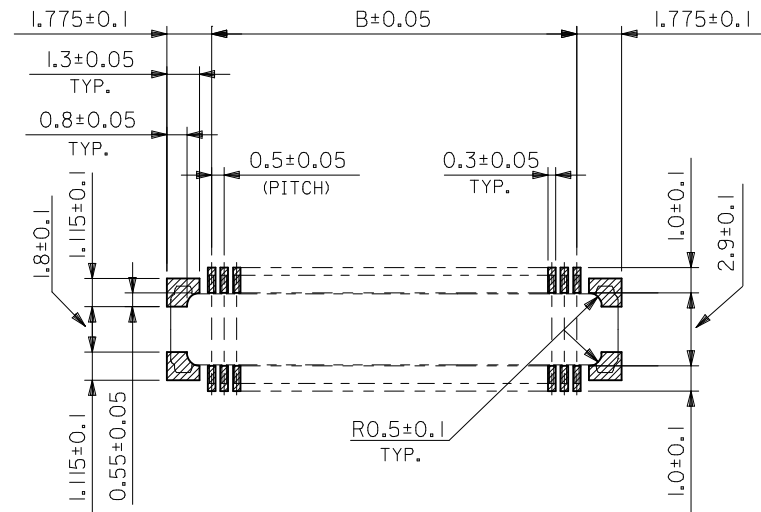
DETAIL H
SCALE 20:1

—#	35.55	36.75	34.5	37.75	55299-1478	55299-1471	140
—#	30.55	31.75	29.5	32.75	55299-1278	55299-1271	120
—#	25.55	26.75	24.5	27.75	55299-1078	55299-1071	100
20	10.55	11.75	9.5	12.75	55299-0478	55299-0471	40
30	8.05	9.25	7	10.25	55299-0378	55299-0371	30
20	5.55	6.75	4.5	7.75	55299-0278	55299-0271	20
□ツク数 LOCKS	D	C	B	A	エンボス梱包品 EMBOSSED TAPE PACKAGING	製品番号 MATERIAL NO.	極数 CIRCUITS

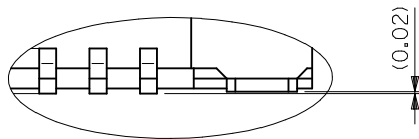
REVISED		MODEL NO. 55292-***71		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
EC NO: J2009-0140	DRWN: YOSHIDAM	2008/07/31	2008/07/31	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE '04/03/09	TITLE		0.5 MM PITCH B/B CONN. PLG HSG ASSY (H=3MM) -LEAD FREE-			
CH'KD: THARUYAMA	2008/07/31	2008/07/31	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/03/09	MOLEX INCORPORATED		SD-55299-010				
APPR: NUKITA	2008/11/21	2008/11/21	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/03/09	DOCUMENT NO.		1 OF 2				
REV	DESCRIPTION	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE		SHEET NO.			
A		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



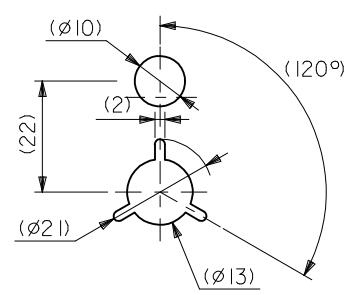
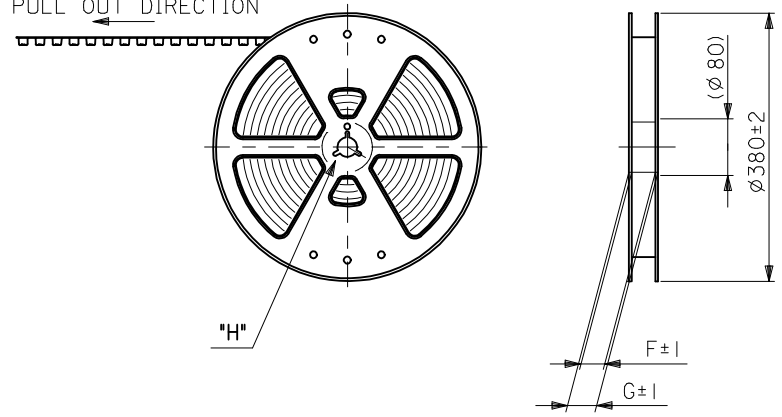
推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE 5:1)



T部詳細
DETAIL T

REVISED EC NO: J2009-0140 DRWN: YOSHIDAM 2008/07/31 CHKD: THARUYAMA 2008/07/31 APPR: NUKITA 2008/11/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE '04/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG HOUSING ASSY(H=3MM) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/03/09	MOLEX INCORPORATED DOCUMENT NO. SD-55299-010 SHEET NO. 2 OF 2			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/03/09				
ANGULAR	±3 °	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

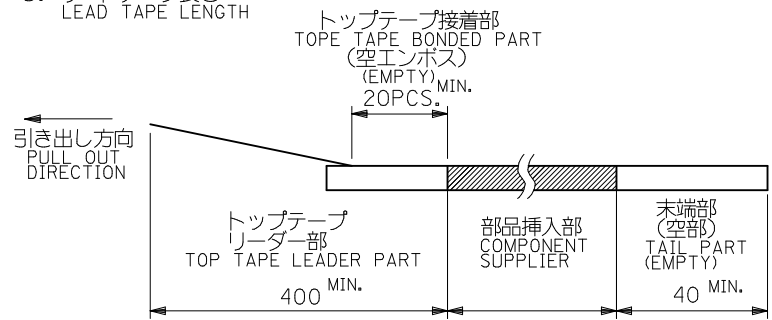
引き出し方向
PULL OUT DIRECTION



DETAIL "H"

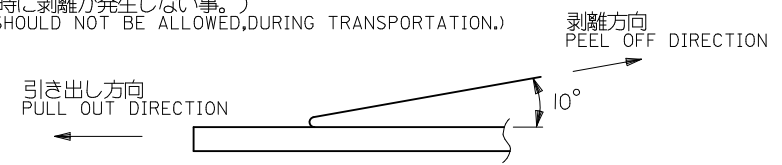
注)
NOTES

1. 製品番号 55299-***71 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55299-***71 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 2000個/リール
NUMBER OF CONNECTORS: 2000 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度: (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0. 1~1. 3N{ 10~130gf }

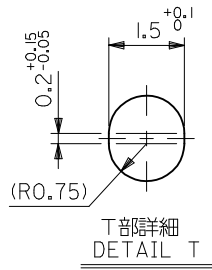
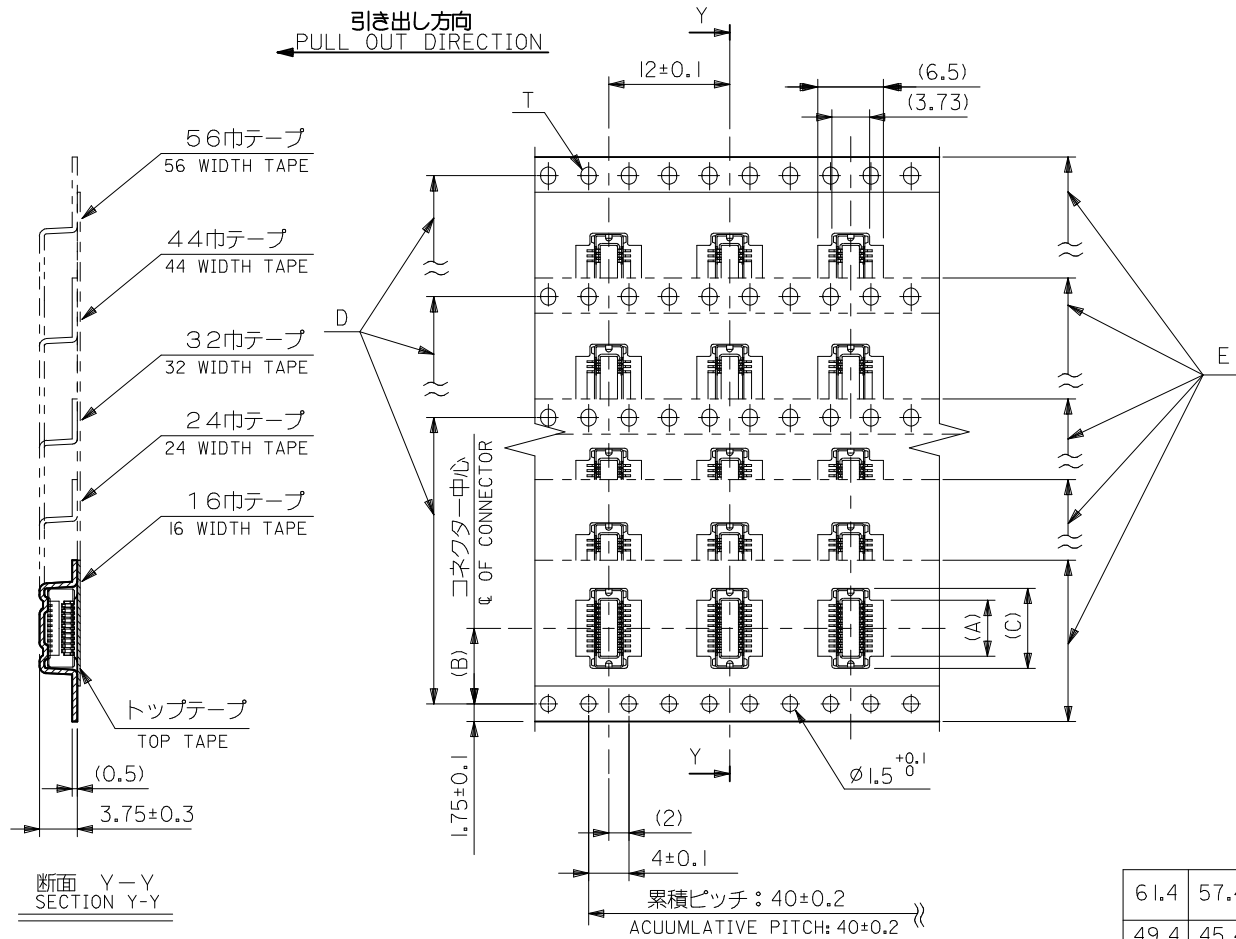
尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.)



5. 材料
MATERIAL
キャリアテープ: ポリプロピレン (PP)
CARRIER TAPE: POLYPROPYLENE (PP)
トップテープ: PET, PE, PEF
TOP TAPE: PET, PE, PEF
リール: ポリスチレン (PS) <リサイクル材を含む>
REEL: POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

6. 本製品は55299-***8の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55299-***8

REVISED EC NO: J2009-0140 DRWN: YOSHIDAM 2008/07/31 CHKD: THARUYAMA 2008/07/31 APPR: NUKITA 2008/11/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY M. NAGATA	DATE '04/03/09	TITLE 55299-***71 TAPING PACKAGE -LEAD FREE-			
	10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE '04/03/09	MOLEX INCORPORATED DOCUMENT NO. SD-55299-011 SHEET NO. 1 OF 2			
	30 OVER	± 0.3	APPROVED BY H. IKESUGI	DATE '04/03/09				
ANGULAR	$\pm 3^\circ$	MATERIAL NO. SEE TABLE						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



断面 Y-Y
SECTION Y-Y

累積ピッチ: 40±0.2
ACCUMLATIVE PITCH: 40±0.2

61.4	57.4	56±0.3	52.4	37.95	26.2	35.55	55299-1478	140	
				32.95		30.55	55299-1278	120	
49.4	45.4	44±0.3	40.4	27.95	20.2	25.55	55299-1078	100	
				12.95	11.5	10.55	55299-0478	40	
29.4	25.4	24±0.3	#	10.45		8.05	55299-0378	30	
				7.95	7.5	5.55	55299-0278	20	
21.4	17.4	16±0.3	#						
G	F	E キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED		MODEL NO. 55299-***78		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
EC NO: J2009-0140		DRWN: YOSHIDAM 2008/07/31		GENERAL TOLERANCES (UNLESS SPECIFIED)		MM ONLY		10:1		METRIC	
CH'KD: THARUYAMA 2008/07/31		APPR: NUKITA 2008/11/21		10 UNDER ±0.2		DRAWN BY M. NABEI		DATE '05/03/10		TITLE	
REV		DESCRIPTION		10 OVER 30 UNDER ±0.25		CHECKED BY K. TOYODO		DATE '05/03/10		55299-***71 TAPING PACKAGE -LEAD FREE-	
				30 OVER ±0.3		APPROVED BY N. UKITA		DATE '05/03/10		MOLEX INCORPORATED	
				ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-55299-011		2 OF 2	
						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			